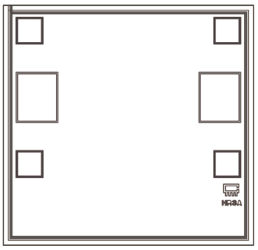
Microwave

Gain Equalizer Die EQY-XX-283-D+ Series

50Ω DC to 28 GHz



The Big Deal

- Excellent Return Loss, 17dB typ.
- Wide bandwidth, DC - 28 GHz
- Usable up to 30GHz

Product Overview

EQY-XX-283-D+ series of absorptive Gain Equalizer dice are fabricated using highly repetitive GaAs IPD* MMIC process incorporating resistors, capacitors and inductors having negative insertion loss slope. EQY-XX-283-D+ are available with nominal attenuation slope of 3, 4, 5 & 6 dB.

Key Features

Feature	Advantages
Negative Insertion Loss Slope vs. Frequency	Useful for compensating negative gain slope of amplifiers, receivers, transmitters to achieve flat gain versus frequency.
Wide range of values 3,4,5 & 6dB	Enables circuit designer to change nominal insertion loss values without board redesign making the EQY-XX-283-D+ Series ideal for select at test application.
Wideband operation, DC to 28 GHz	Supports a wide array of applications including wireless cellular, microwave communications, satellite, defense and aerospace, medical broadband and optic applications.
Excellent Power Handling Capability	Enables its use at the output of a variety of amplifiers
Unpackaged Die	Enables the user to integrate the gain equalizer directly into hybrids.

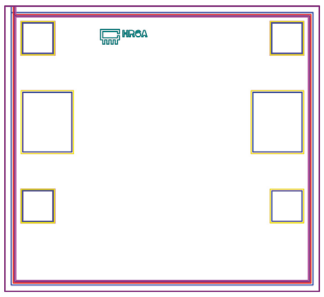
*GaAs IPD (Gallium Arsenide Integrated Passive Device)

Microwave

Gain Equalizer Die

EQY-6-283-D+

50Ω 6dB DC to 28 GHz



Product Features

- 6.0 dB Slope from DC to 28 GHz
  Can work up to 30 GHz
- Good Return Loss, 17 dB typ.

Typical Applications

- Cellular Infrastructure
- 5G
- Wideband Communications
- Test Instrumentation
- Defense

+RoHS Compliant

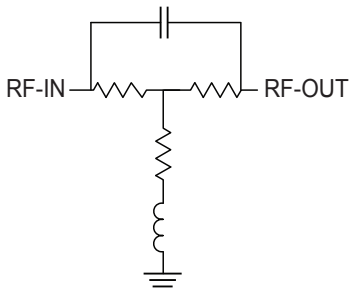
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Ordering Information: Refer to Last Page

General Description

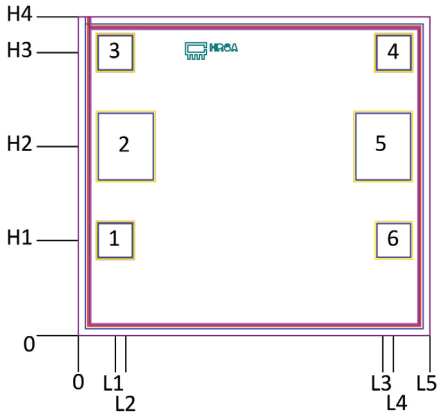
EQY-6-283-D+ is an absorptive Gain Equalizer Die fabricated using highly repetitive GaAs IPD MMIC process incorporating resistors, capacitors and inductors having negative insertion loss slope. EQY-6-283-D+ has a nominal attenuation slope of 6.0 dB.

Simplified Schematic and Pad description



Pad Number	Description
2	RF-Input pad
5	RF-Output pad
1,3,4,6 & Bottom of Die	Ground

Bonding Pad Position



Dimensions in µm, Typical

L1	L2	L3	L4	L5	H1	H2	H3	H4	Thickness	Die Size	Pad Size 2 & 5	Pad Size 1,3,4,6
79	101	650	673	750	204	404	644	680	100	750x680	117x142	72x72

Electrical Specifications[1] at 25°C, 50Ω, unless otherwise noted.

Parameter	Condition (GHz)	Min.	Typ.	Max.	Units
Frequency Range		DC		28	GHz
Insertion Loss	0.01	—	6.6	—	dB
	10	—	4.5	—	
	20	—	1.7	—	
	28	—	0.6	—	
	30	—	0.6	—	
VSWR	0.01 - 10	—	1.10	—	:1
	10 - 20	—	1.15	—	
	20 - 28	—	1.15	—	
	28-30	—	1.17	—	

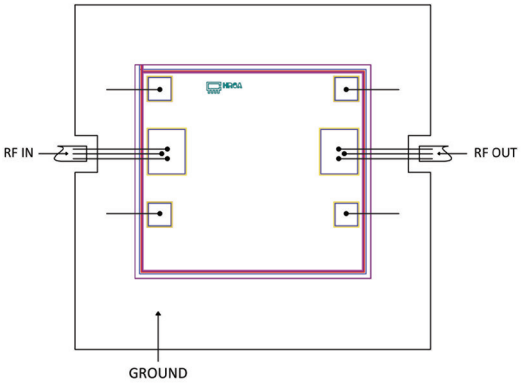
1. Electrical specifications are measured with die being packaged in 2x2 6L MCLP and mounted on Characterization Test Board TB-EQY-6-283+.

Absolute Maximum Ratings[2]

Operating Case Temperature	-55°C to 105°C
RF Input Power[3]	28 dBm

2. Permanent damage may occur if any of these limits are exceeded.
3. Derates linearly to 24dBm at 105°C

Assembly Diagram



Assembly and Handling Procedure

1. Storage
   Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD
   MMIC GaAs Gain equalizer dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static worksta tion. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach
   The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are Ablestik 84-1LMISR4 or equivalent. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy cover age around total die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recom mended to use antistatic die pick up tools only.
4. Wire Bonding
   Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

Additional Detailed Technical Information

additional information is available on our dash board.

Performance Data	Data Table	
	Swept Graphs	
	S-Parameter (S2P Files) Data Set with and without port extension(.zip file)	
Case Style	Die	
Die Ordering and packaging information	Quantity, Package	Model No.
	Small, Gel - Pak: 5,10,50,100 KGD*	EQY-6-283-DG+
	Medium†, Partial wafer: KGD*<2070	EQY-6-283-DP+
	†*Available upon request contact sales representative*	
	Refer to AN-60-067	
Environmental Ratings	ENV80	

*Known Good Die (KGD) means that the die are taken from PCM good wafer and then visually inspected per Mini-Circuits' criteria. Though this is not definitive, it does provide a higher degree of confidence that die are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

ESD Rating**

Human Body Model (HBM): Class 2 (Pass 2000V) in accordance with ANSI/ESD STM 5.1 - 2001

** Tested in industry standard 2 x 2mm, 6-lead MCLP package

Additional Notes

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.

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Mini-Circuits

Environmental Specifications ENV80

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85° C or -40° to 105° C or -55° to 105° C or -45° to 105° C Ambient Environment	Refer to Individual Model Data Sheet
Storage Environment (Die)	-65° to 150°C	Individual Model Data Sheet
Storage Environment(Packaging)	-40° to 70°C and 40 to 60% humidity (In Factory Shipped Package)	

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